
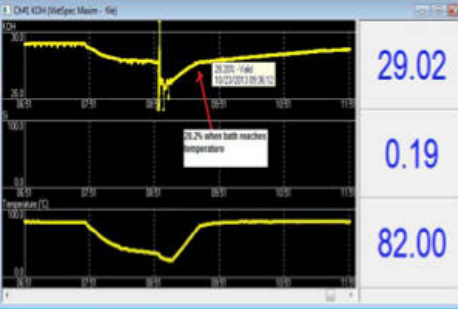



Wet Etching Process Application Solution

		
<p>Consistent Etch <i>Consistent Results — Via Smart, Closed Loop Controls</i></p>	<p>Top Etch Uniformity <i>Consistent Results — Wafer to Wafer & Lot to Lot</i></p>	<p>Advanced Hardware/Software <i>Process Understanding & Execution Process</i></p>

Superior KOH Etch Solution

Advanced Hardware, Process Understanding and Software Execution

Consistent Etch Performance

- Via closed loop process control
- Advanced tank designs and flow controls
- Rapid robot transfer to rinse in less than five seconds

Etch Rate Uniformity (200mm)

- Wafer to wafer < 1%
- Within wafer < 1%
- Lot to lot < 1%
- Tank to tank < 1%

No Contamination

- Particle neutral at 0.12 μ
- Metallic contamination < 1E10
- Integrated dryer

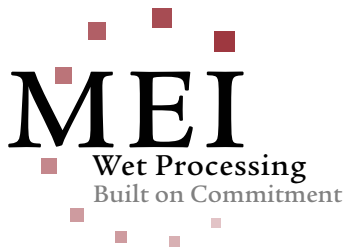
Etch Stability Concentration Control

- Hyper accurate concentration controls (ABB, Horiba, CI Semi)
- Hyper accurate spiking capability (chemical and DI)
- Automatic compensation for losses due to consumption and evaporation

Increased Reliability

- MTBF < 1500 Hr (Semi E10)
- Avg MTTR < 1 Hr
- Higher uptime > 95%
- Reduced scrap
- No complex wafer handling

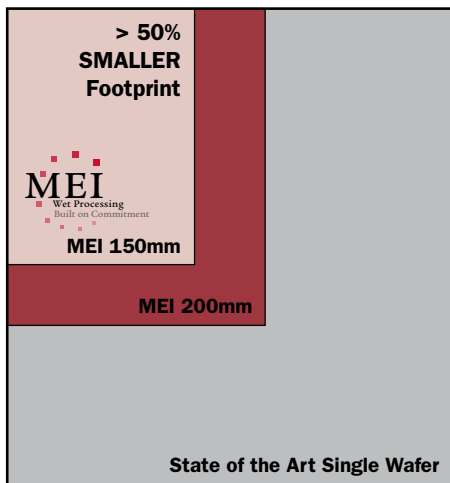




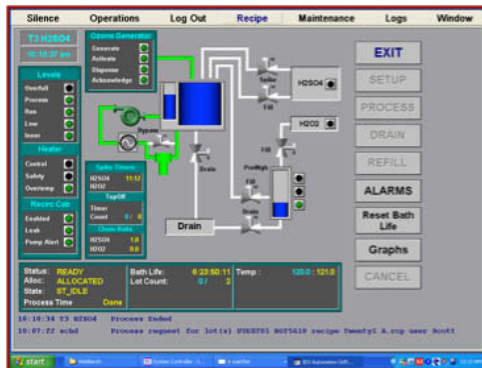
MEI Wet Processing Systems & Services, LLC
 3838 Western Way NE
 Albany, OR 97321
 Phone 1-541-917-3626
www.meillc.com

SiEtch

Small Footprint



Immersion Tools Generally Have Much Smaller Footprints Than Comparable WPH Single Wafer Tools



Etch Control Through Advanced Hardware, Process Understanding and Software Execution

KOH Concentration Control

- Feed and bleed chemical controls
- Integrated bulk or manual fill KOH spike reservoirs
- IDX Flexware software controls by closed loop feedback
- In-line KOH, silicate & DI concentration sensor
- Software control of concentration by closed loop feedback from NIR sensor
- Etch uniformity equal or better than single wafer systems
- Lower chemical cost per wafer processed
- Dramatically reduces the need for check and repeat etch steps

MEI Platform Advantages

Multi Lot Simultaneous Processing

- High performance, shared control system, shared facilities, smaller footprint

Advanced Software Capabilities

- User programmable configuration
- Chemical and DI water spiking

Proven Stability

- Rapid transfer from etch to rinse
- Agitation flexibility

Automation Reliability

- Field proven designs



Superior Process Control

- SECS/GEM compliant
- Recipe editor
- Advanced process controls
- Unlimited user/permission levels
- Easy-to-use, touch-screen interface
- Error logging and data graphing
- User programmable configuration
- Recipes, speeds, chem control
- Barcode reader compatibility
- Remote access compatible
- I/O monitor displays status

Analog Control

Analog sensing enables software to control:

- In-tank blending
- Blending ratio creation
- Control DI water inject
- Control temperature
- Recirculation flow
- Spiking volume

MEI's Award Winning Service and Support

MEI Global Field Service Team

- Final test and verification
- Standard one year parts and labor warranty
- Two year optional warranty
- Full field service support, on-site warranty coverage
- On-site training provided

